

# SN54AS1032A, SN74AS1032A QUADRUPLE 2-INPUT POSITIVE-OR BUFFERS/DRIVERS

SDAS072B – DECEMBER 1982 – REVISED JANUARY 1995

- Driver Version of 'AS32
- High Capacitive-Drive Capability
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

## description

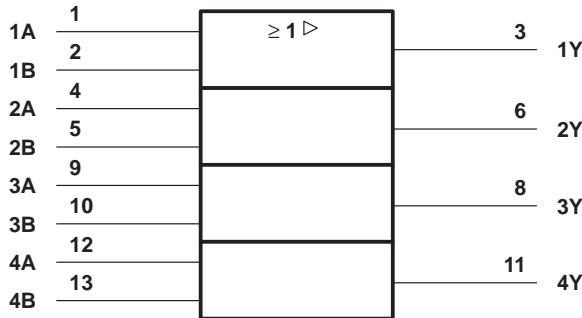
These devices contain four independent 2-input positive-OR buffers/drivers. They perform the Boolean functions  $Y = A + B$  or  $Y = \overline{A} \cdot \overline{B}$  in positive logic.

The SN54AS1032A is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74AS1032A is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

FUNCTION TABLE  
(each gate)

INPUTS		OUTPUT Y
A	B	
H	X	H
X	H	H
L	L	L

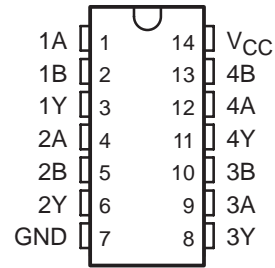
## logic symbol†



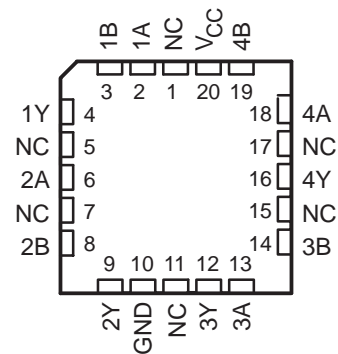
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

SN54AS1032A . . . J PACKAGE  
SN74AS1032A . . . D OR N PACKAGE  
(TOP VIEW)

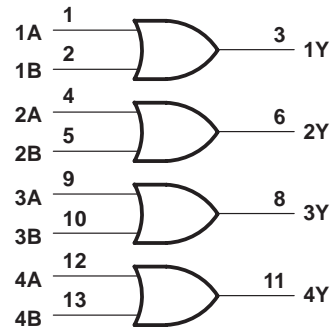


SN54AS1032A . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## logic diagram (positive logic)



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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, $V_{CC}$	7 V
Input voltage, $V_I$	7 V
Operating free-air temperature range, $T_A$ : SN54AS1032A	-55°C to 125°C
SN74AS1032A	0°C to 70°C
Storage temperature range	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions‡

	SN54AS1032A			SN74AS1032A			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$ Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$ High-level input voltage	2			2			V
$V_{IL}$ Low-level input voltage			0.8			0.8	V
$I_{OH}$ High-level output current			-40			-48	mA
$I_{OL}$ Low-level output current			40			48	mA
$T_A$ Operating free-air temperature	-55		125	0		70	°C

‡ These high sink- or source-current devices are not recommended for use above 40 MHz.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS1032A			SN74AS1032A			UNIT
		MIN	TYP§	MAX	MIN	TYP§	MAX	
$V_{IK}$	$V_{CC} = 4.5 V$ , $I_I = -18 mA$			-1.2			-1.2	V
$V_{OH}$	$V_{CC} = 4.5 V$ to $5.5 V$ , $I_{OH} = -2 mA$	$V_{CC} - 2$			$V_{CC} - 2$			V
	$V_{CC} = 4.5 V$		2.4	3.2		2.4	3.2	
		$I_{OH} = -3 mA$	2			2		
$V_{OL}$	$V_{CC} = 4.5 V$	$I_{OH} = -40 mA$						
		$I_{OH} = -48 mA$				2		
$V_{OL}$	$V_{CC} = 4.5 V$	$I_{OL} = 40 mA$	0.25	0.5				V
		$I_{OL} = 48 mA$				0.35	0.5	
$I_I$	$V_{CC} = 5.5 V$ , $V_I = 7 V$			0.1			0.1	mA
$I_{IH}$	$V_{CC} = 5.5 V$ , $V_I = 2.7 V$			20			20	μA
$I_{IL}$	$V_{CC} = 5.5 V$ , $V_I = 0.4 V$			-0.5			-0.5	mA
$I_{O}^{\parallel}$	$V_{CC} = 5.5 V$ , $V_O = 2.25 V$	-50		-200	-50		-200	mA
$I_{CCH}$	$V_{CC} = 5.5 V$ , $V_I = 4.5 V$		7.7	11.5		7.7	11.5	mA
$I_{CCL}$	$V_{CC} = 5.5 V$ , $V_I = 0$		14.7	24		14.7	24	mA

§ All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^\circ C$ .

¶ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .



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## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54AS1032A		SN74AS1032A		
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	1	7	1	6.3	ns
t <sub>PHL</sub>			1	7	1	6.3	

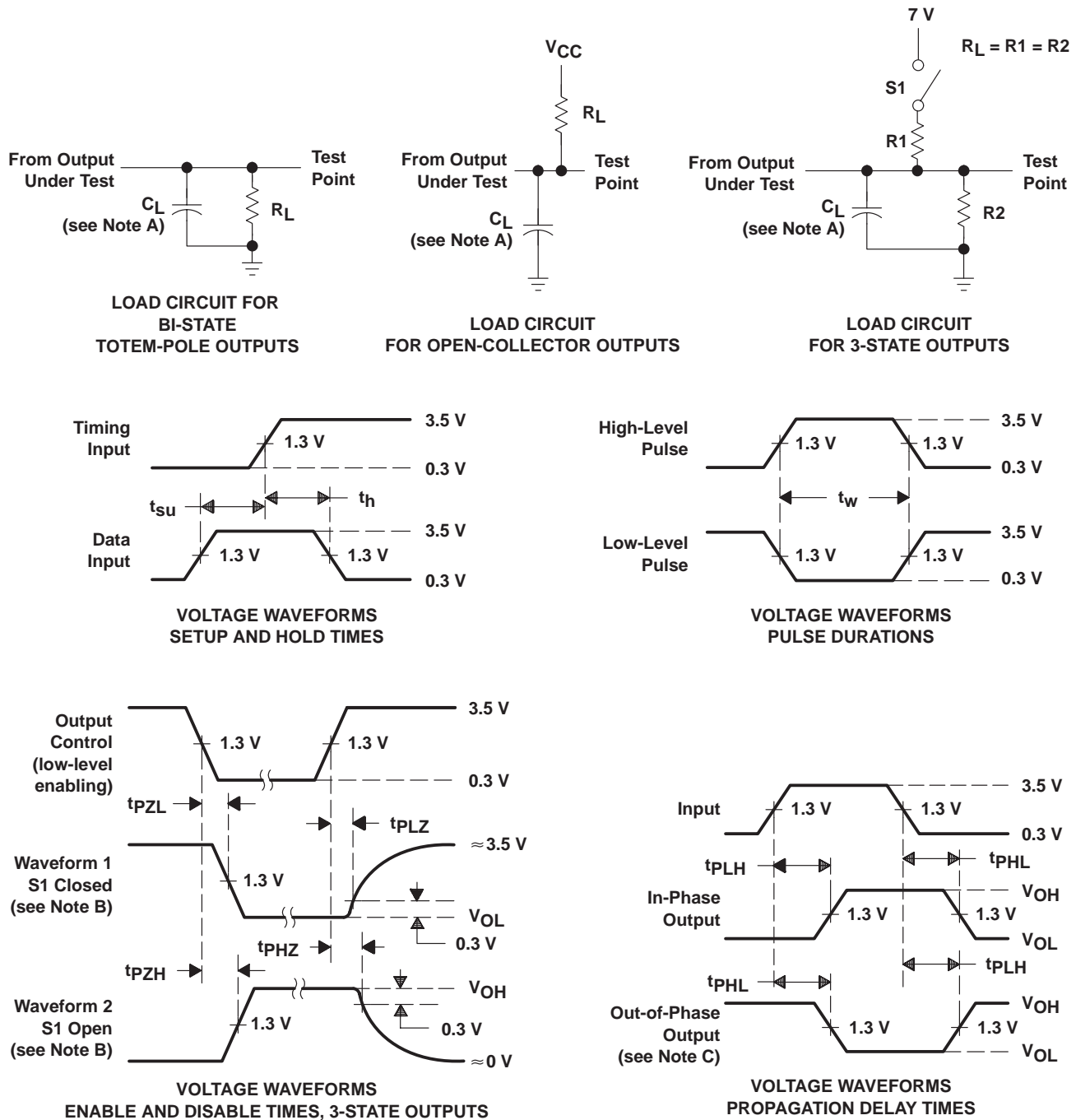
† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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## PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.  
 D. All input pulses have the following characteristics:  $PRR \leq 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.  
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-88730012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
5962-8873001DA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SN54AS1032AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74AS1032AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS1032ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS1032ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS1032AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS1032ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54AS1032AFK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54AS1032AJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004



N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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